

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	RYOTA HODO	06/11/2015
	MOTOMU KURATA	06/11/2015
	SHINYA SASAGAWA	06/11/2015
RECEIVING PARTY DATA		
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City:	ATSUGI-SHI, KANAGAWA-KEN	
State/Country:	JAPAN	
Postal Code:	243-0036	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14739127	
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NAME OF SUBMITTER:	JANELLE A. JACKSON	
SIGNATURE:	/Janelle A. Jackson/	
DATE SIGNED:	06/19/2015	
Total Attachments: 1		
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ASSIGNMENT

For valuable consideration, We, Ryota HODO of Isehara, Kanagawa, Japan, Motomu KURATA of Isehara, Kanagawa, Japan and Shinya SASAGAWA of Chigasaki, Kanagawa, Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd., a Japanese corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE, filed June 15, 2015, and assigned U.S. Serial Number 14/739,127, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature Ryota HODO
Name: Ryota HODO
Date: 06/11/2015

Signature Motomu KURATA
Name: Motomu KURATA
Date: 06/11/2015

Signature Shinya SASAGAWA
Name: Shinya SASAGAWA
Date: 06/11/2015